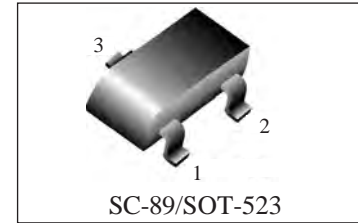


Dual Series Schottky Barrier Diodes

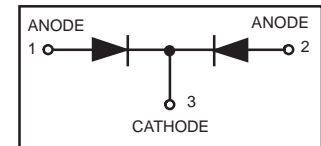
These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

- Extremely Fast Switching Speed
- Low Forward Voltage — 0.35 Volts (Typ) @ $I_F = 10 \text{ mAdc}$



ORDERING INFORMATION

Device	Marking	Shipping
FDR54CE	L3	3000/Tape&Reel



MAXIMUM RATINGS ($T_J = 125^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	30	Volts
Forward Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	150 1.8	mW mW/ $^\circ\text{C}$
Forward Current (DC)	I_F	200 Max	mA
Junction Temperature	T_J	150 Max	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted) (EACH DIODE)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage ($I_R = 10 \mu\text{A}$)	$V_{(BR)R}$	30	—	—	Volts
Total Capacitance ($V_R = 1.0 \text{ V}$, $f = 1.0 \text{ MHz}$)	C_T	—	7.6	10	pF
Reverse Leakage ($V_R = 25 \text{ V}$)	I_R	—	0.5	2.0	μAdc
Forward Voltage ($I_F = 0.1 \text{ mAdc}$)	V_F	—	0.22	0.24	Vdc
Forward Voltage ($I_F = 30 \text{ mAdc}$)	V_F	—	0.41	0.5	Vdc
Forward Voltage ($I_F = 100 \text{ mAdc}$)	V_F	—	0.52	1.0	Vdc
Reverse Recovery Time ($I_F = I_R = 10 \text{ mAdc}$, $I_{R(REC)} = 1.0 \text{ mAdc}$) Figure 1	t_{rr}	—	—	5.0	ns
Forward Voltage ($I_F = 1.0 \text{ mAdc}$)	V_F	—	0.29	0.32	Vdc
Forward Voltage ($I_F = 10 \text{ mAdc}$)	V_F	—	0.35	0.40	Vdc
Forward Current (DC)	I_F	—	—	200	mAdc
Repetitive Peak Forward Current	I_{FRM}	—	—	300	mAdc
Non-Repetitive Peak Forward Current ($t < 1.0 \text{ s}$)	I_{FSM}	—	—	600	mAdc

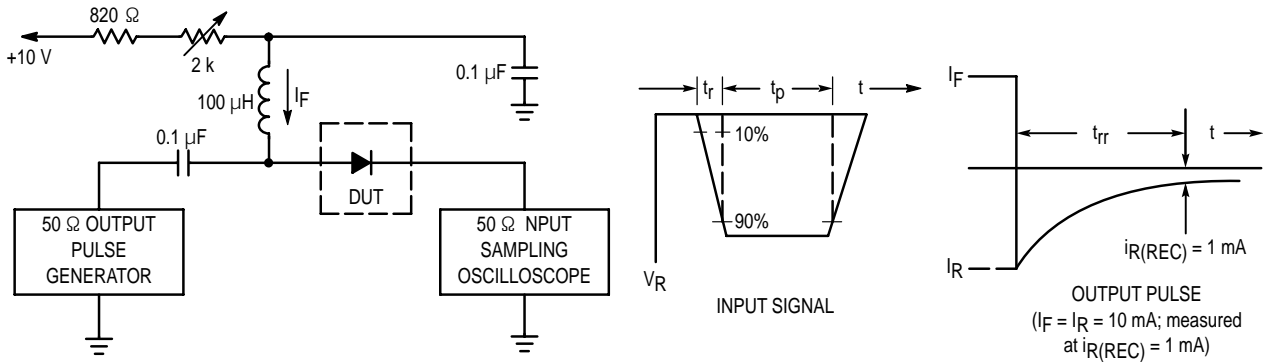


Figure 1. Recovery Time Equivalent Test Circuit

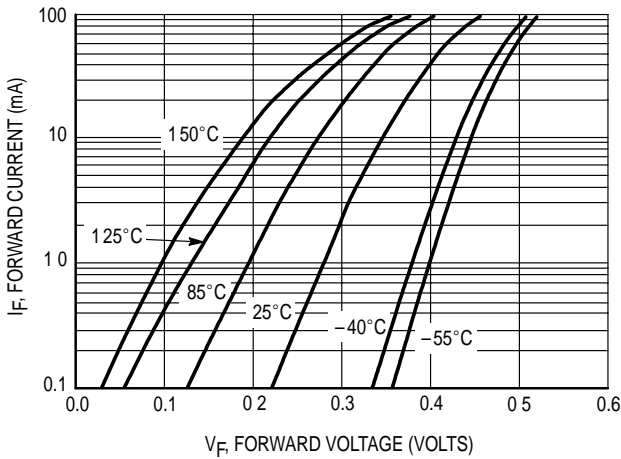


Figure 2. Forward Voltage

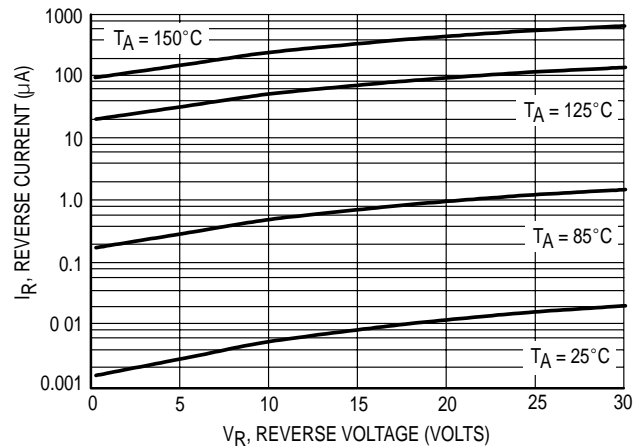


Figure 3. Leakage Current

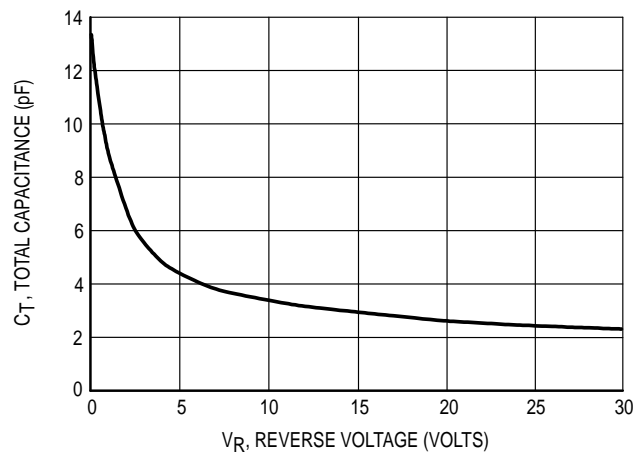
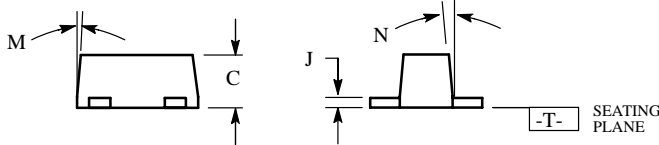
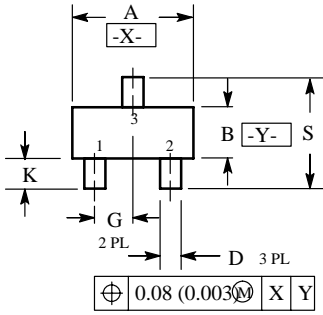


Figure 4. Total Capacitance

SC-89/SOT-523



NOTES:

- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
- 2 CONTROLLING DIMENSION: MILLIMETERS
- 3 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- 4 463C-01 OBSOLETE, NEW STANDARD 463C-02

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.60	1.70	0.059	0.063	0.067
B	0.75	0.85	0.95	0.030	0.034	0.040
C	0.60	0.70	0.80	0.024	0.028	0.031
D	0.23	0.28	0.33	0.009	0.011	0.013
G	0.50BSC			0.020BSC		
H	0.53RBF			0.021RBF		
J	0.10	0.15	0.20	0.004	0.006	0.008
K	0.30	0.40	0.50	0.012	0.016	0.020
L	1.10RBF			0.043RBF		
M	-	-	10°	-	-	10°
N	-	-	10°	-	-	10°
S	1.50	1.60	1.70	0.059	0.063	0.067

